

# Simulation of Electrical Characteristics on Inhomogeneous Strains in Normally-off HEMTs with p-GaN Gate

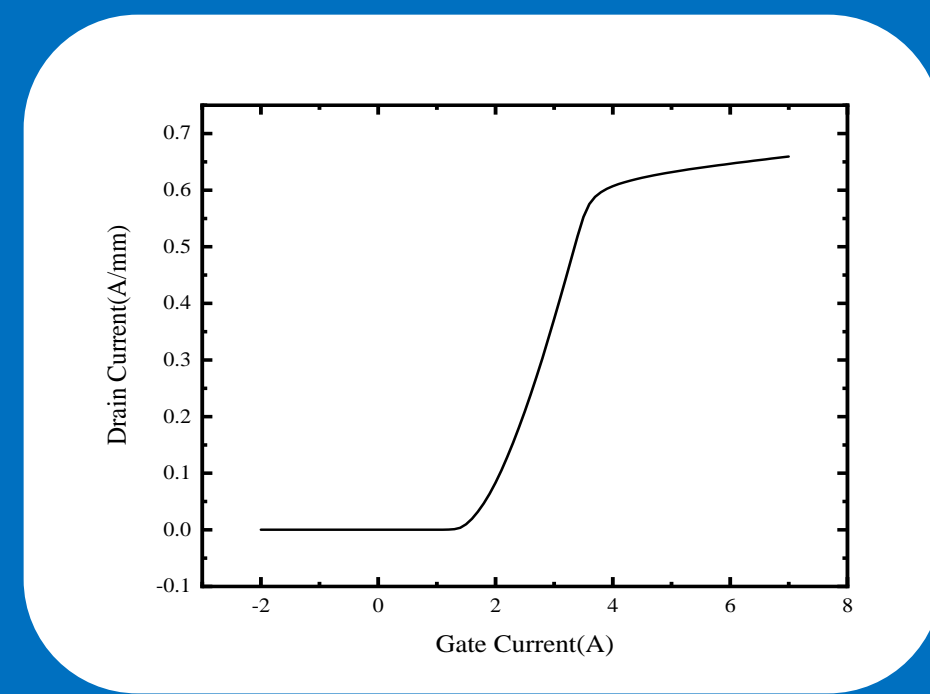
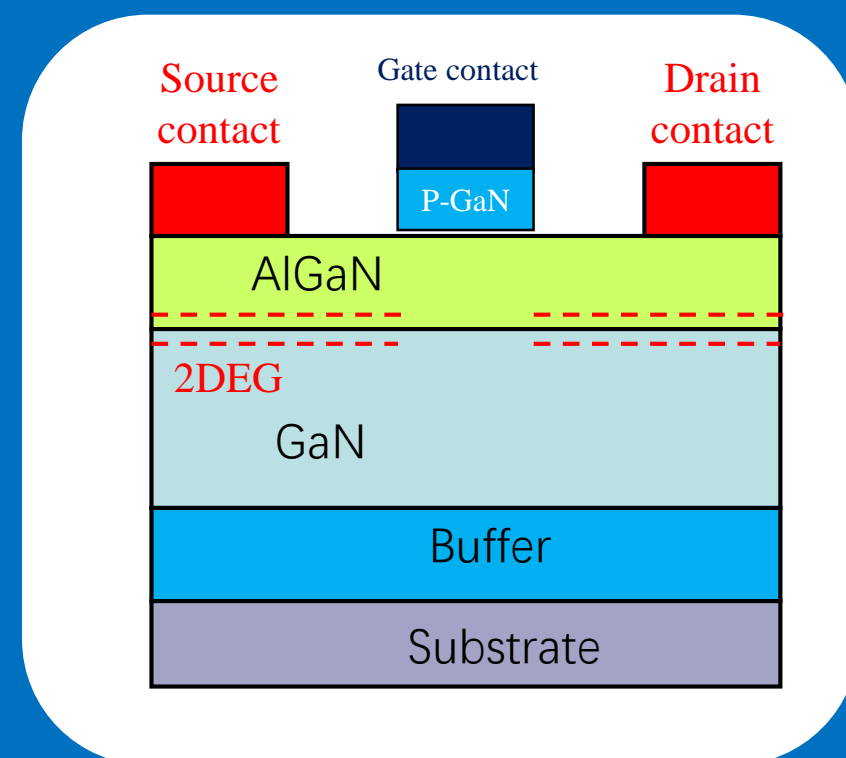
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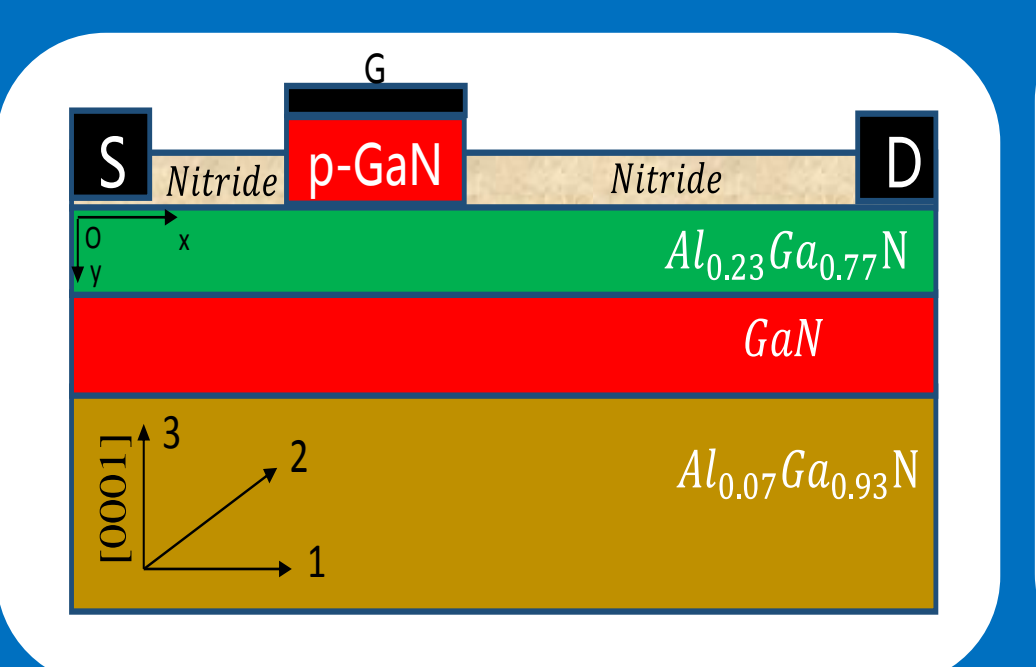
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## Introduction

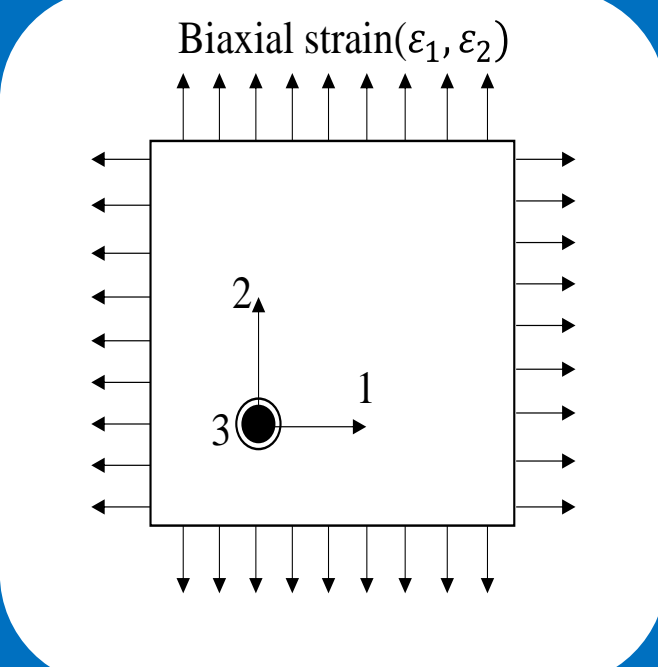
- ◆ High Electron Mobility Transistors (HEMTs) based on AlGaIn/GaN heterostructures became attractive candidates for high switching frequency, high breakdown voltage and high power due to their excellent electrical properties, compared to their silicon (Si) counterparts[1]
- ◆ Several approaches have been reported to obtain normally-off GaN-based HEMTs, to date the most typical way to yield a normally-off device is the use of a p-GaN gate
- ◆ gate bias-induced or passivation layer-induced inhomogeneous strain in the AlGaIn barrier will cause a decrease in polarization charge and reduction in two dimensional electron gas 2DEG, which will affect electrical characteristics of devices



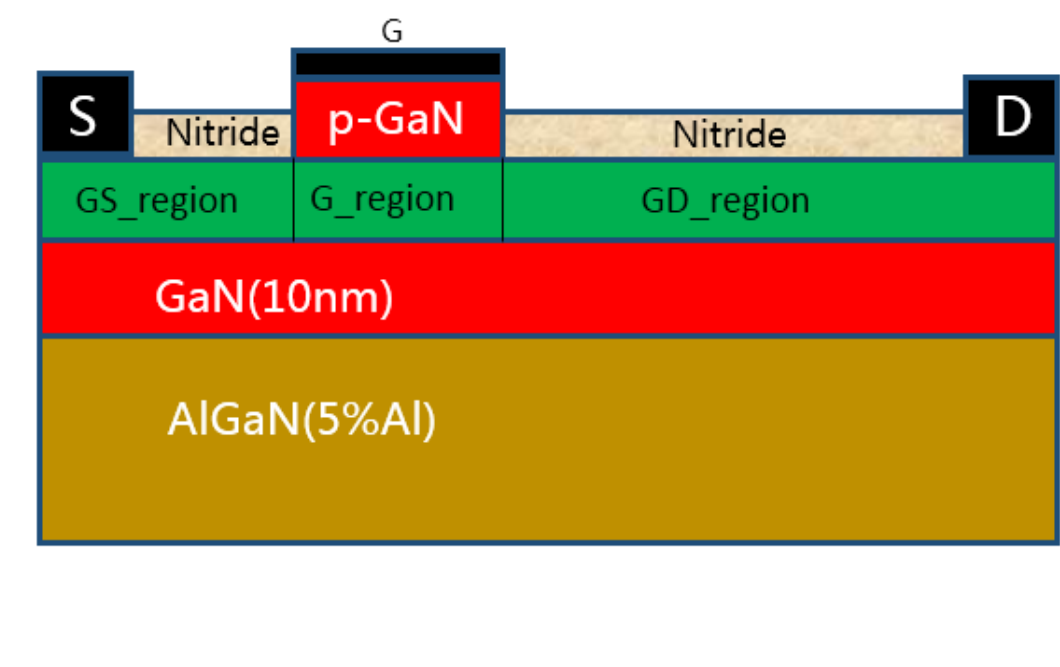
## Structure Model and Analysis Method



Schematic diagram of HEMT



HEMT under biaxial applied strain



Schematic diagram of HEMT under inhomogeneous strain

- We simulated the uneven stress (biaxial strain) of the three regions by adjusting the lattice constants[2] of the materials in the three regions of the AlGaIn barrier layer, and observed the effect of non-uniform strain on the electrical characteristics of the device.

$$\epsilon'_1 = \epsilon'_2 = \frac{a - a_0}{a_0}, \quad \epsilon'_3 = -2 \frac{C_{13}}{C_{33}} \epsilon'_1$$

## Conclusion

In Region-G or gate region, the strain has the most predominant impact on  $V_{br}$  with  $a$  decreasing of 39%, while  $I_{sat}$  with an increasing of 97% as the  $a$  increases from 3.173061Å to 3.187229Å. In addition, the  $V_{br}$  can be improved with 12% by strain between the gate and drain electrode or Region-GD when the  $a$  increases.

## Results

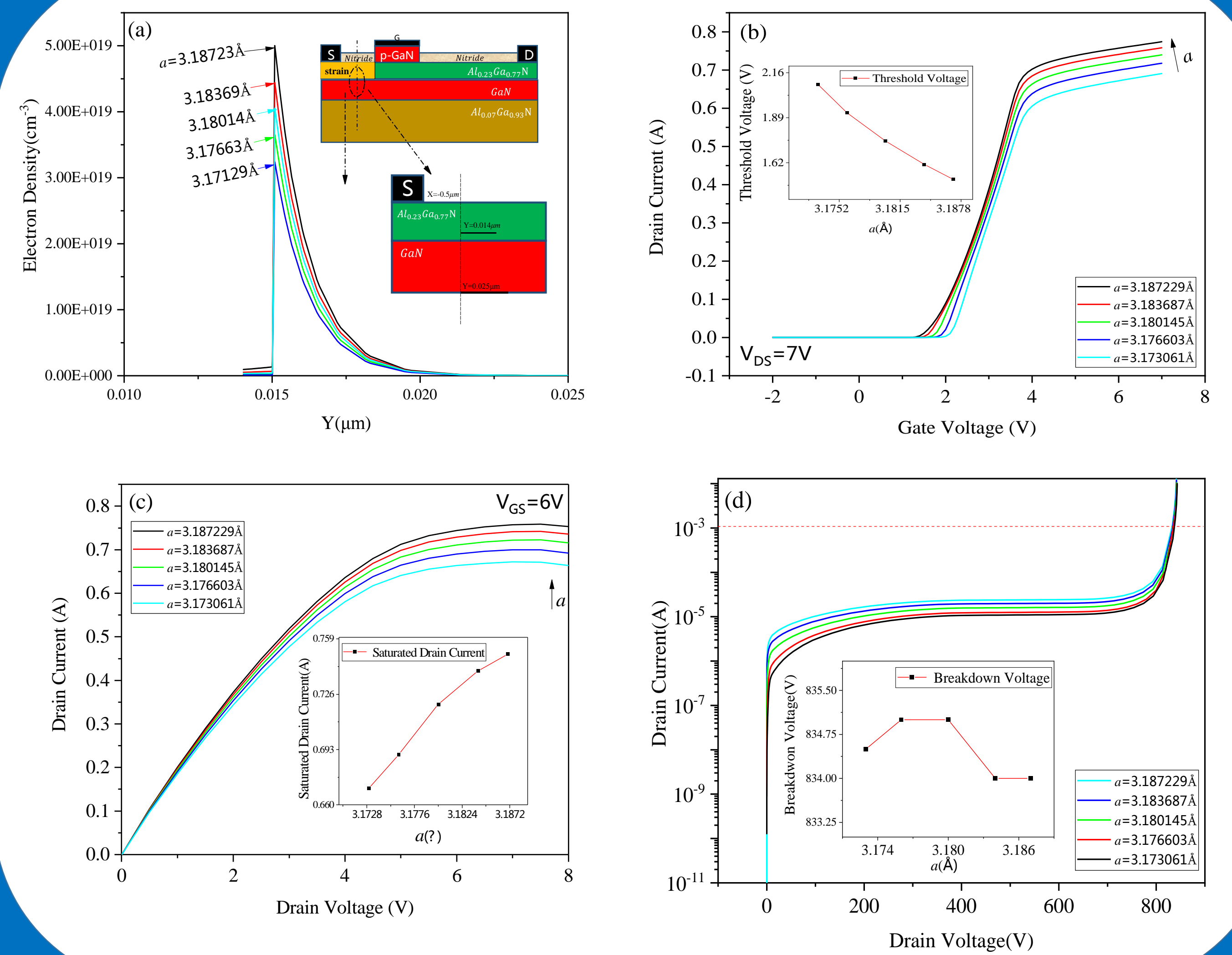
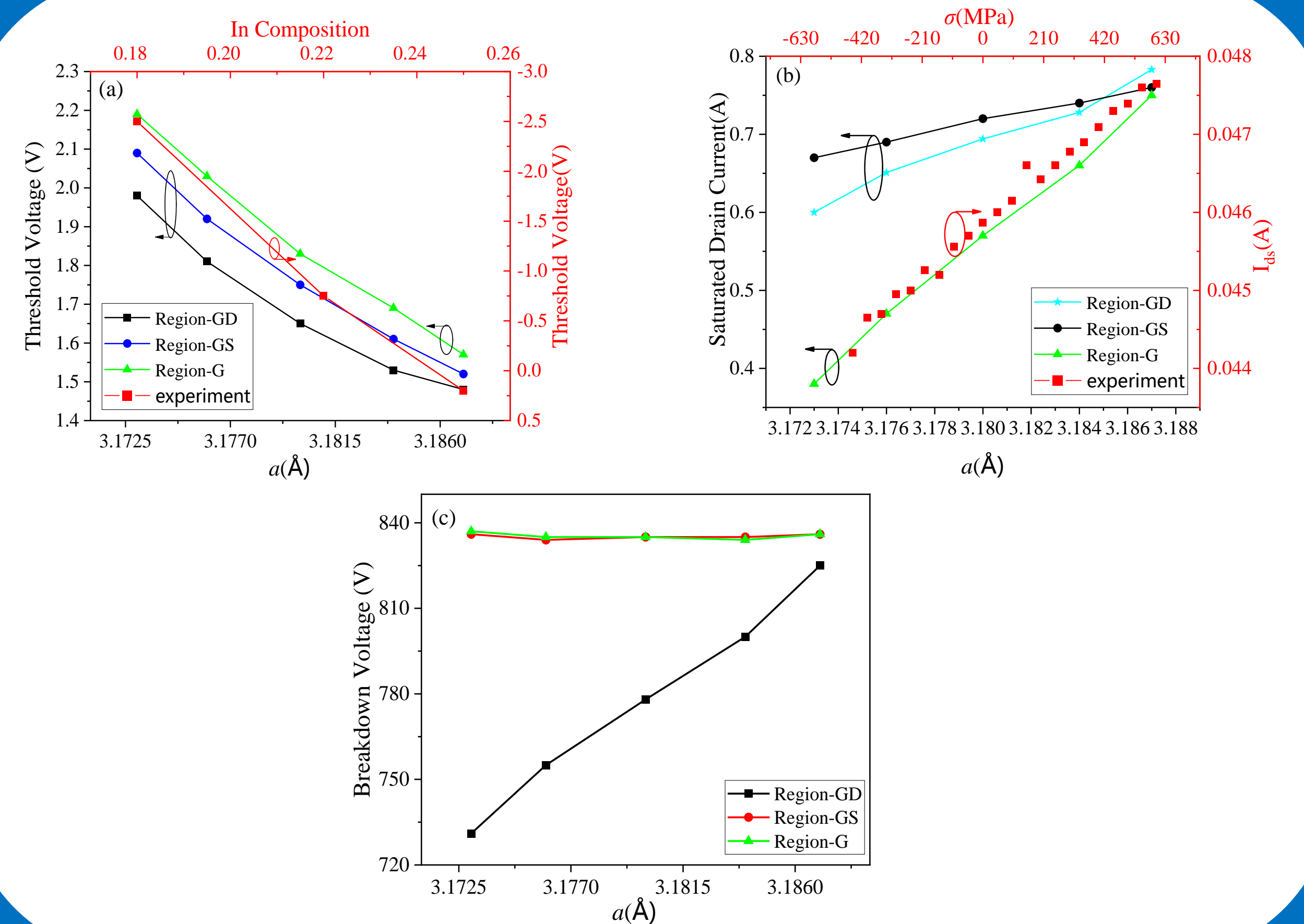


Fig.1 The impact of strained lattice constant  $a$  in Region-GS on electrical characteristics. (a) the cross-sectional 2DEG density at  $x = -0.5\mu\text{m}$  where the peak 2DEG density was located close to the AlGaIn/GaN interface. (b) transfer characteristics. (c) output characteristics. (d) breakdown characteristics. The insets give the change of  $V_{th}$ ,  $I_{sat}$ ,  $V_{br}$  against strained lattice constant  $a$ .

- Strain-enhanced  $V_{th}$  can be derived from reduced density of 2DEG in the Region-GS, and the gate voltage required to open the channel shift positively
- This reduction in  $I_{sat}$  may be caused by the lower density of 2DEG due to a smaller  $a$  in the Region-GS which affecting the sheet resistance and current drive
- The results in Fig.1(d) denote that local strain in Region-G has a little impact on the off-state breakdown characteristics

## Results



The relationship between the strained lattice constant  $a$  of Region-GS, Region-G and Region-GD in HEMT and the electrical features, compared to the experimental data: (a) the threshold voltage  $V_{th}$ , (b) the drain saturation current  $I_{sat}$ , and (c) the breakdown voltage  $V_{br}$ .

- The results indicate that strain in Region-G has the most significant influence on  $V_{th}$
- Strain in Region-G has the most influence on  $I_{sat}$
- The breakdown voltage has an evident positive shift under the strain of Region-GD